

Qucs

Compact device - circuit macromodel specification

A Curtice level 1 MESFET model

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Introduction

The Metal and Semiconductor FET (MESFET) is a Schottky-barrier gate FET made from gallium arsenide. It is popular for high frequency applications because of its high electron mobility. The device was developed by Walter R. Curtice¹ in 1980 at the RCA Laboratory in Princeton, New Jersey. USA. The MESFET model presented below is based on a Qucs equation defined device (EDD) which functions as a Curtice level 1 MESFET model with interelectrode capacitances. Basic temperature effects are also included.

Qucs EDD model for the Curtice MESFET

Parameters

Name	Symbol	Description	Unit	Default
RG	R_G	external gate resistance	Ω	1m
RD	R_D	external drain resistance	Ω	1m
RS	R_S	external source resistance	Ω	1m
VBR	V_{DR}	GS breakdown voltage	V	10^{10}
LG	L_G	external gate lead inductance	H	0
LD	L_D	external drain lead inductance	H	0
LS	L_S	external source lead inductance	H	0
Is	I_S	diode saturation current	A	10f
N	N	diode emission coefficient		1
XTI	X_{TI}	diode saturation current temperature coefficient		0
EG	E_G	diode energy gap	eV	1.11
TAU	τ	internal time delay from drain to source	s	10p
RIN	R_{IN}	series resistance to CGS	Ω	1m
CGS	C_{GS}	interelectrode gate-source bias-independent capacitance	F	300f
CGD	C_{GD}	interelectrode gate-drain bias-independent capacitance	F	300f
CDS	C_{DS}	interelectrode drain-source bias-independent capacitance	F	300f
Tnom	T_{NOM}	device parameter measurement temperature	$^{\circ}\text{C}$	27
Temp	T	device temperature	$^{\circ}\text{C}$	27
Alpha	α	coefficient of Vds in tanh function for quadratic model	1/V	0.8

¹W.R Curtice, 1980, A MESFET model for use in the design of GaAs integrated circuits, IEEE Transactions on Microwave Theory and Techniques, MTT-28, pp. 448-456.

Name	Symbol	Description	Unit	Default
Beta	β	transconductance parameter	A/V ²	3m
Lambda	λ	channel length modulation parameter for quadratic model	1/V	40m
VTO	V_{TO}	quadratic model gate threshold voltage	V	-6

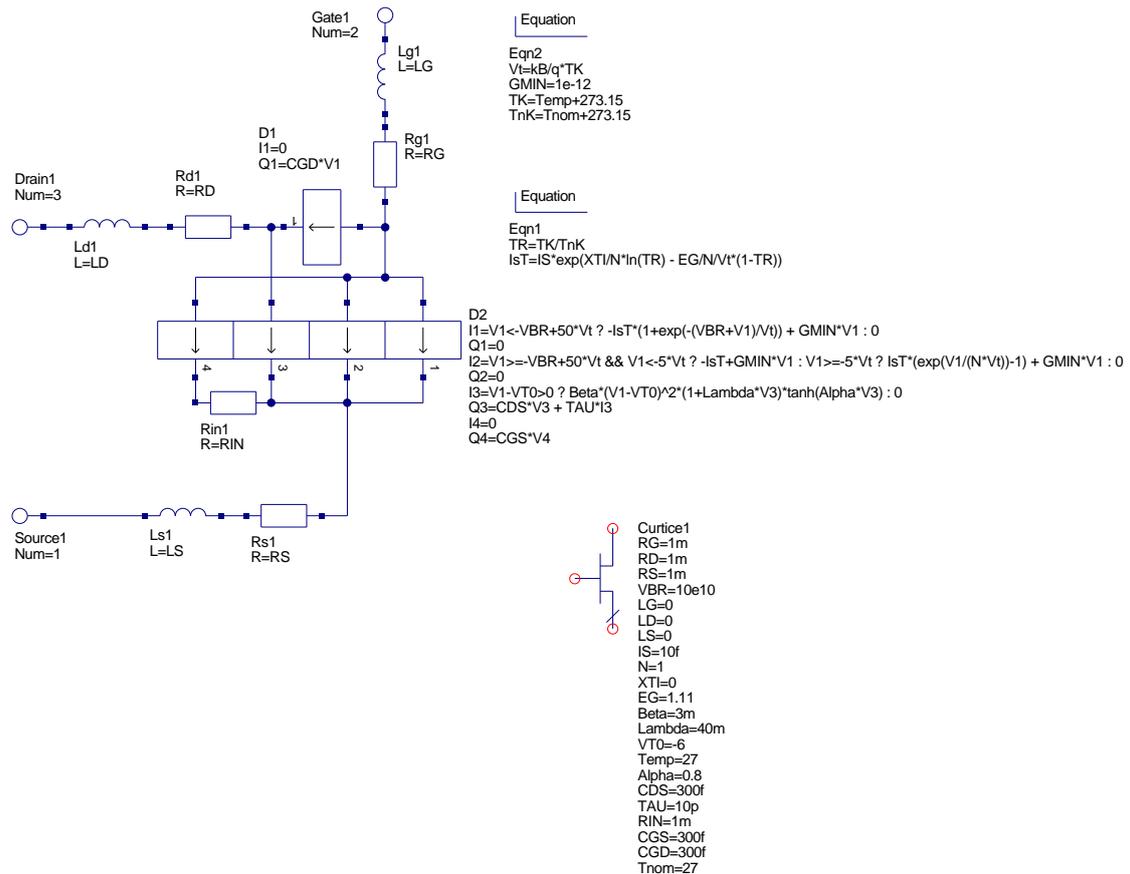


Figure 1: A Qucs EDD model for the Curtice MESFET

The MESFET equations

- DC characteristics

1. for ($V_{GS} < -V_{BR} + 50 \cdot V_T$)

$$I_{GS} = -I_S(T) \cdot \left(1 + \exp\left(-\frac{V_{BR} + V_{GS}}{V_T}\right) \right) + G_{MIN} \cdot V_{GS} \quad (1)$$

2. for ($V_{GS} \geq -V_{BR} + 50 \cdot V_T$) and ($V_{GS} < -5 \cdot V_T$)

$$I_{GS} = -I_S(T) + G_{MIN} \cdot V_{GS} \quad (2)$$

3. for ($V_{GS} \geq -5 \cdot V_T$)

$$I_{GS} = I_S(T) \cdot \left(\exp\left(\frac{V_{GS}}{N \cdot V_T}\right) - 1 \right) + G_{MIN} \cdot V_{GS} \quad (3)$$

4. for ($V_{GS} - V_{TO}) > 0$

$$I_{DS} = \beta \cdot (V_{GS} - V_{TO})^2 \cdot (1 + \lambda \cdot V_{DS}) \cdot \tanh(\alpha \cdot V_{DS}) \quad (4)$$

Where

$$I_S(T) = I_S \cdot \exp\left(\frac{X_{TI}}{N} \cdot \ln(TR) - (E_G/N/V_T) \cdot (1 - TR)\right) \quad (5)$$

$$Tr = \frac{TK}{TnK} \quad \text{and} \quad TK = T + 273.15, \quad TnK = T_{NOM} + 273.15 \quad (6)$$

- MESFET charge equations

- 1.

$$Q_{GS} = C_{GS} \cdot V_{GS} \quad (7)$$

- 2.

$$Q_{GD} = C_{GD} \cdot V_{GD} \quad (8)$$

- 3.

$$Q_{DS} = C_{DS} \cdot V_{DS} + \tau \cdot I_{DS} \quad (9)$$

Test circuits and simulation results

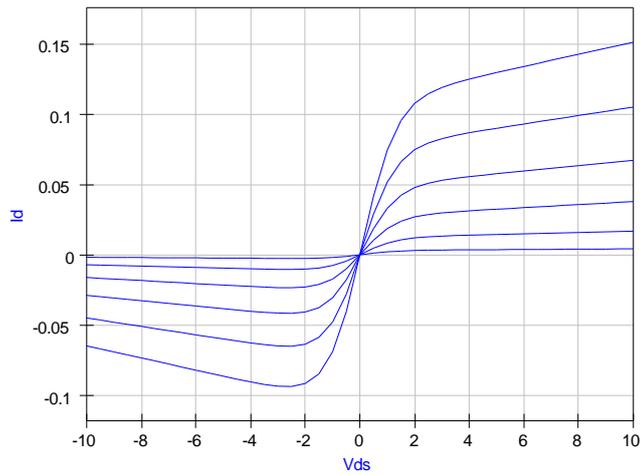
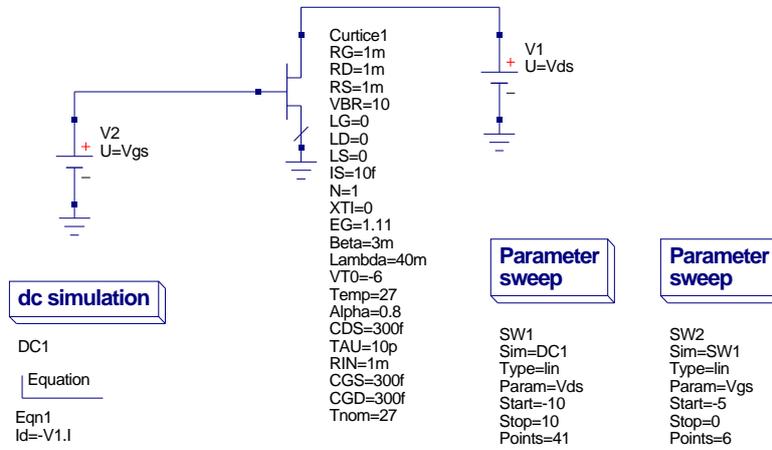


Figure 2: DC test circuit and I_d - V_{ds} characteristics

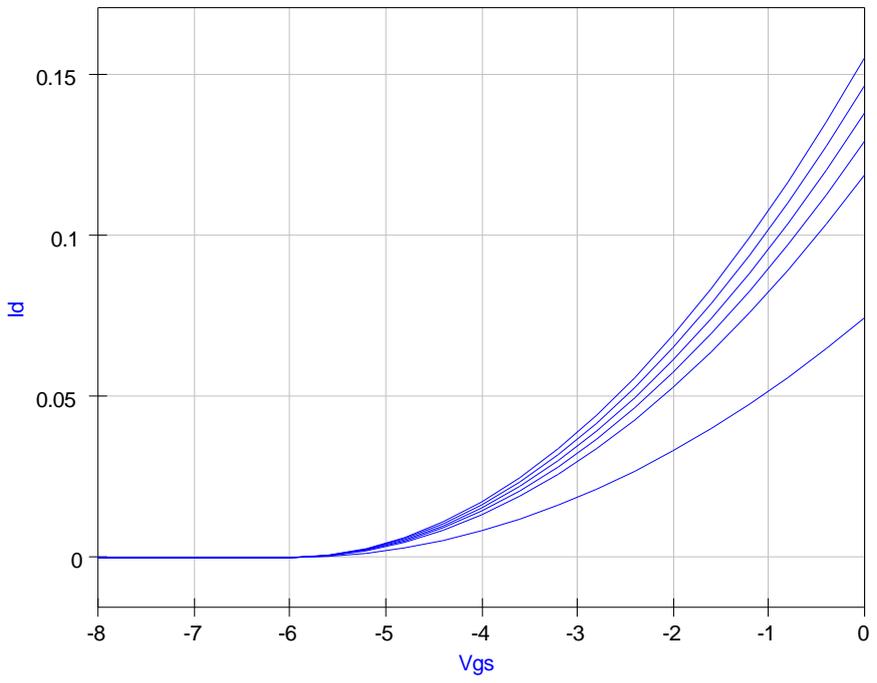
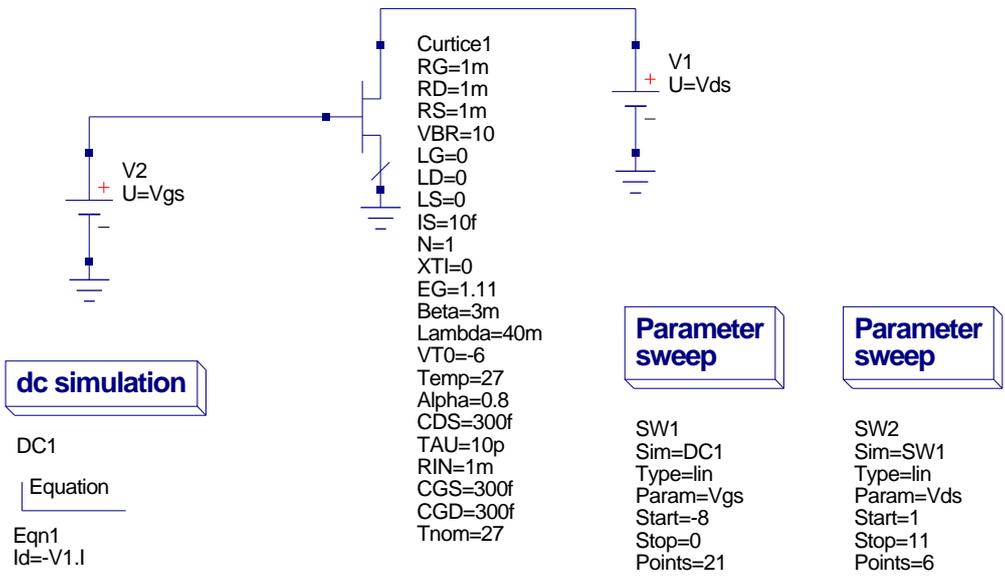


Figure 3: DC test circuit and Id-Vgs characteristics

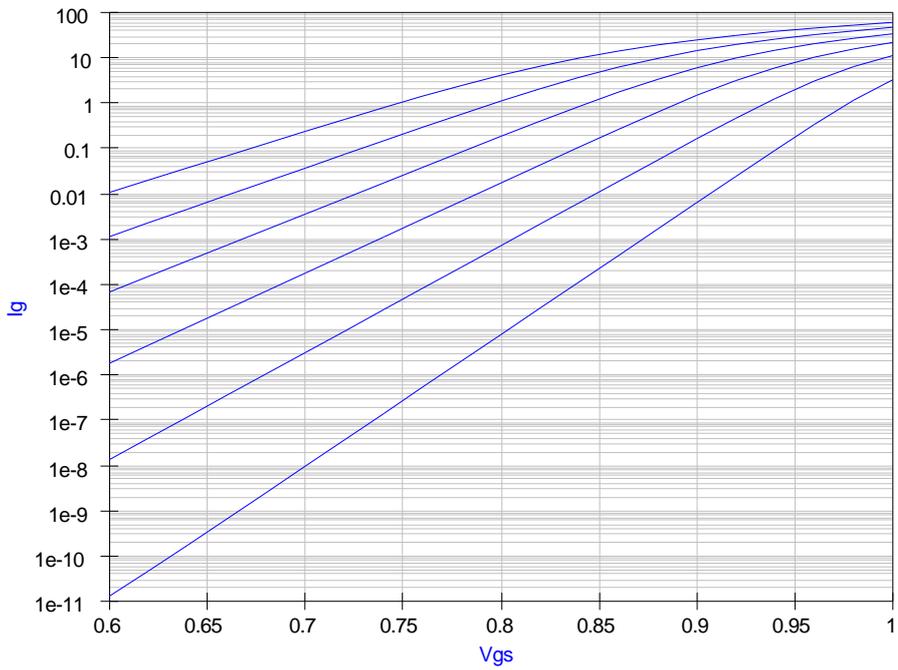
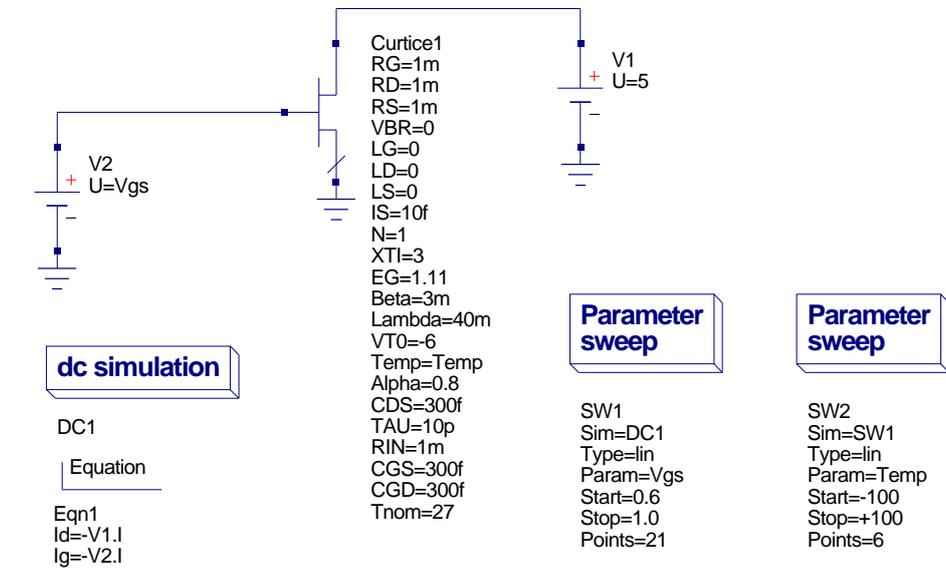


Figure 4: DC test circuit and I_g - V_{gs} characteristics

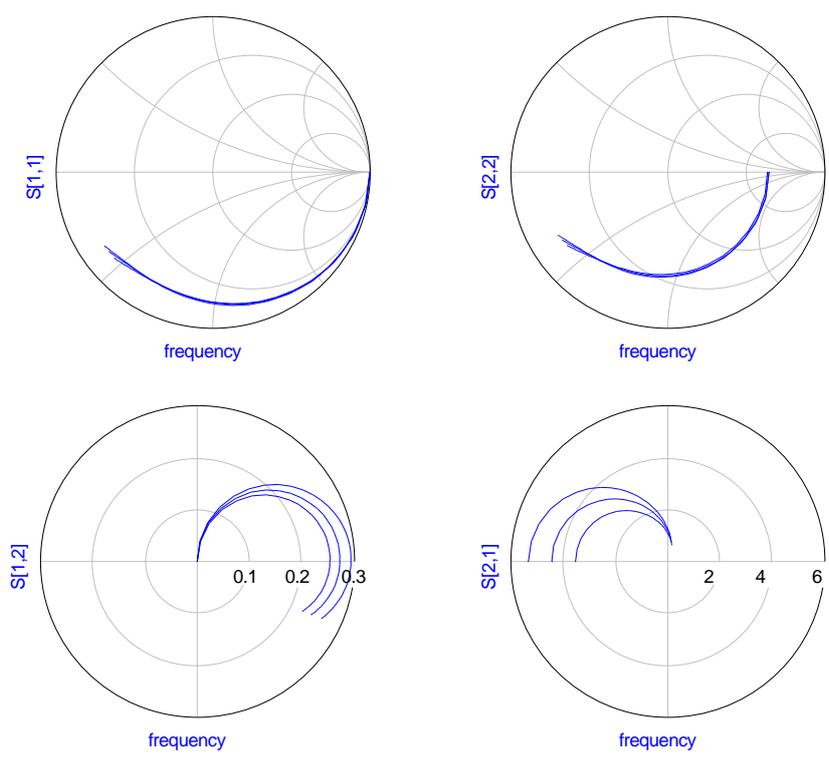
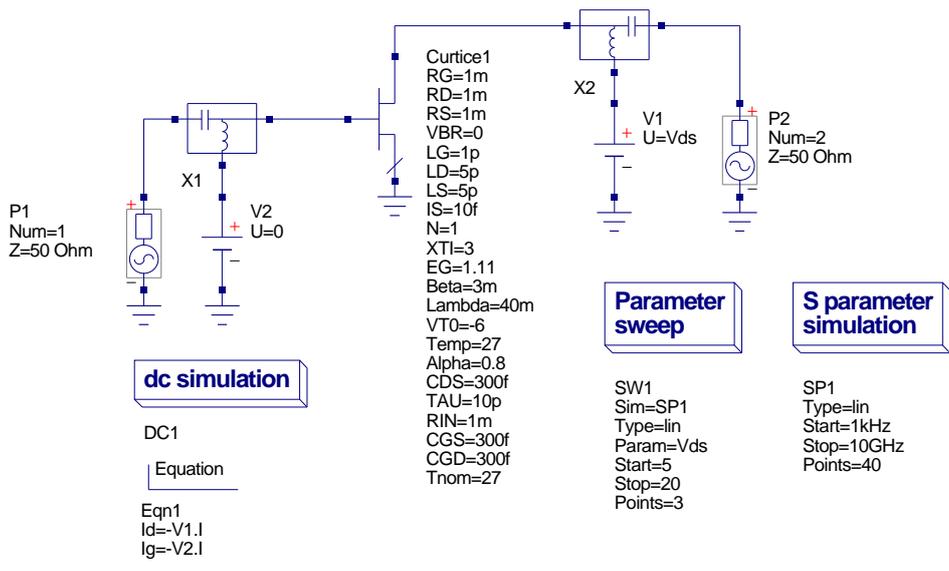


Figure 5: S parameter test circuit and characteristics